



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

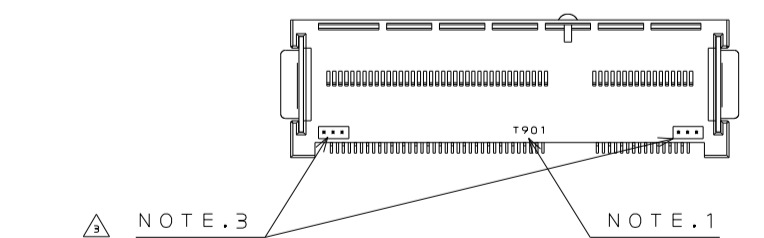
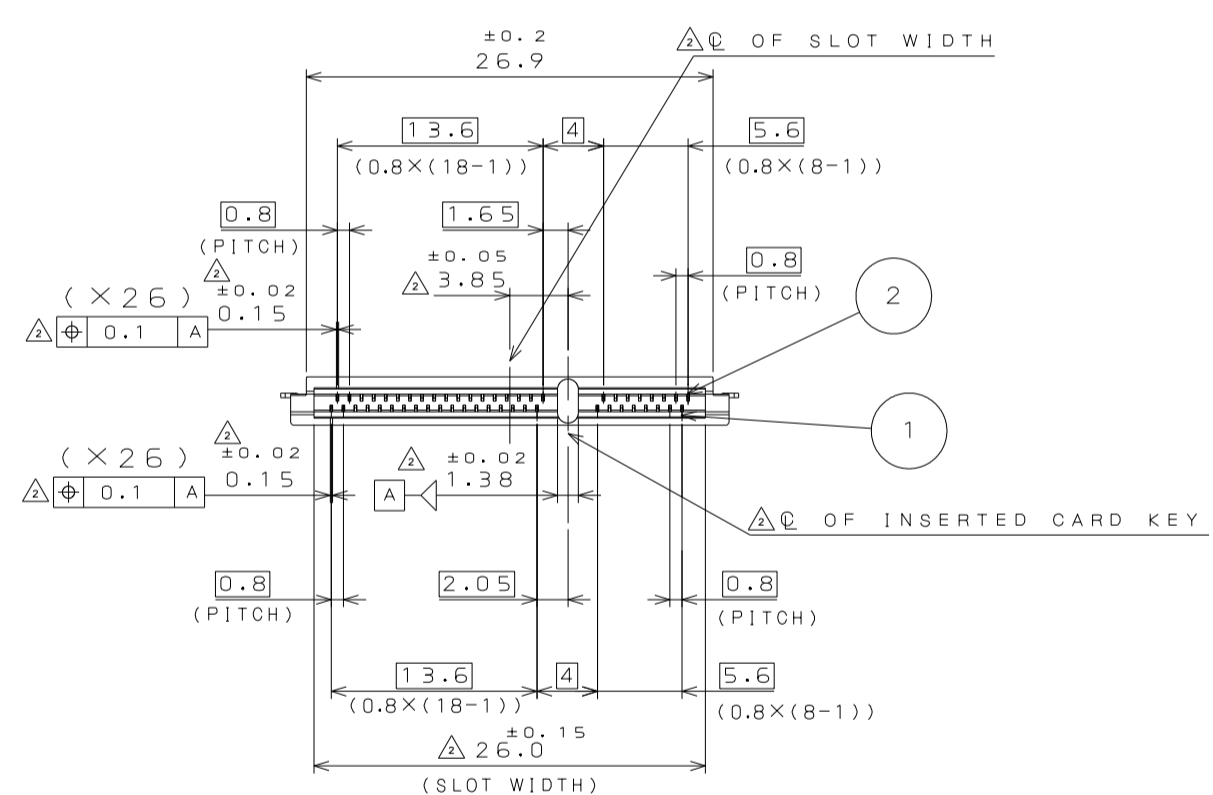
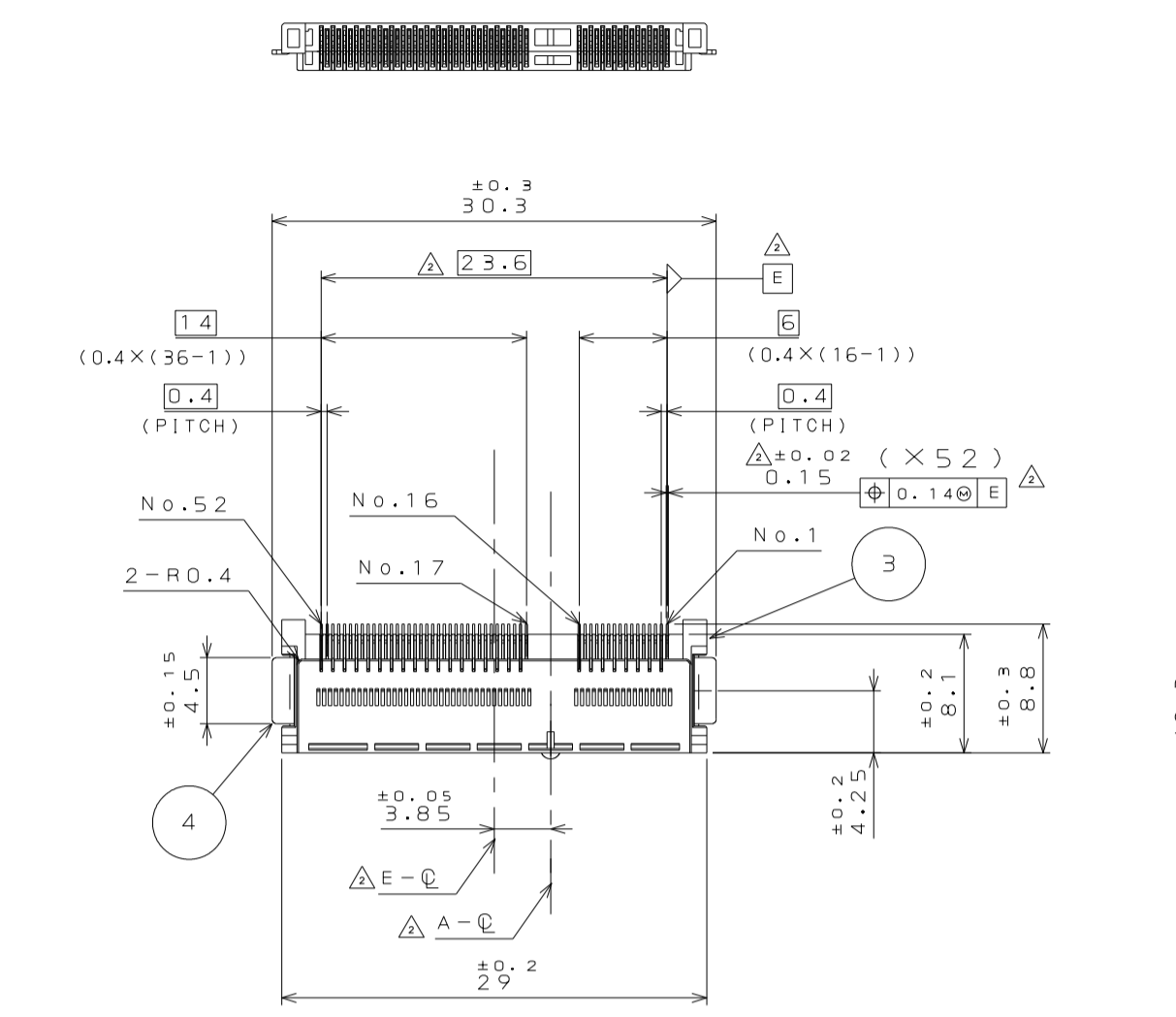
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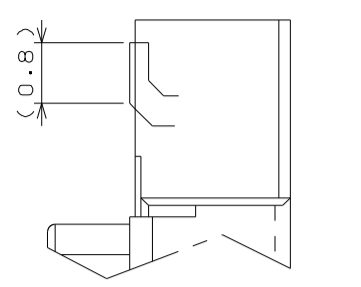


REV. NO.	DATE	DCN. NO.	DESCRIPTION	DR.	CHK.	APPD.	APPD.
2	12.Sep.2011	000245	REVISED DIMENSION		H.KOIZUMI	R.KATO	K.SHINDOU
3	6.Oct.2011	000272	ADD NOTE 3		H.KOIZUMI	R.KATO	K.SHINDOU

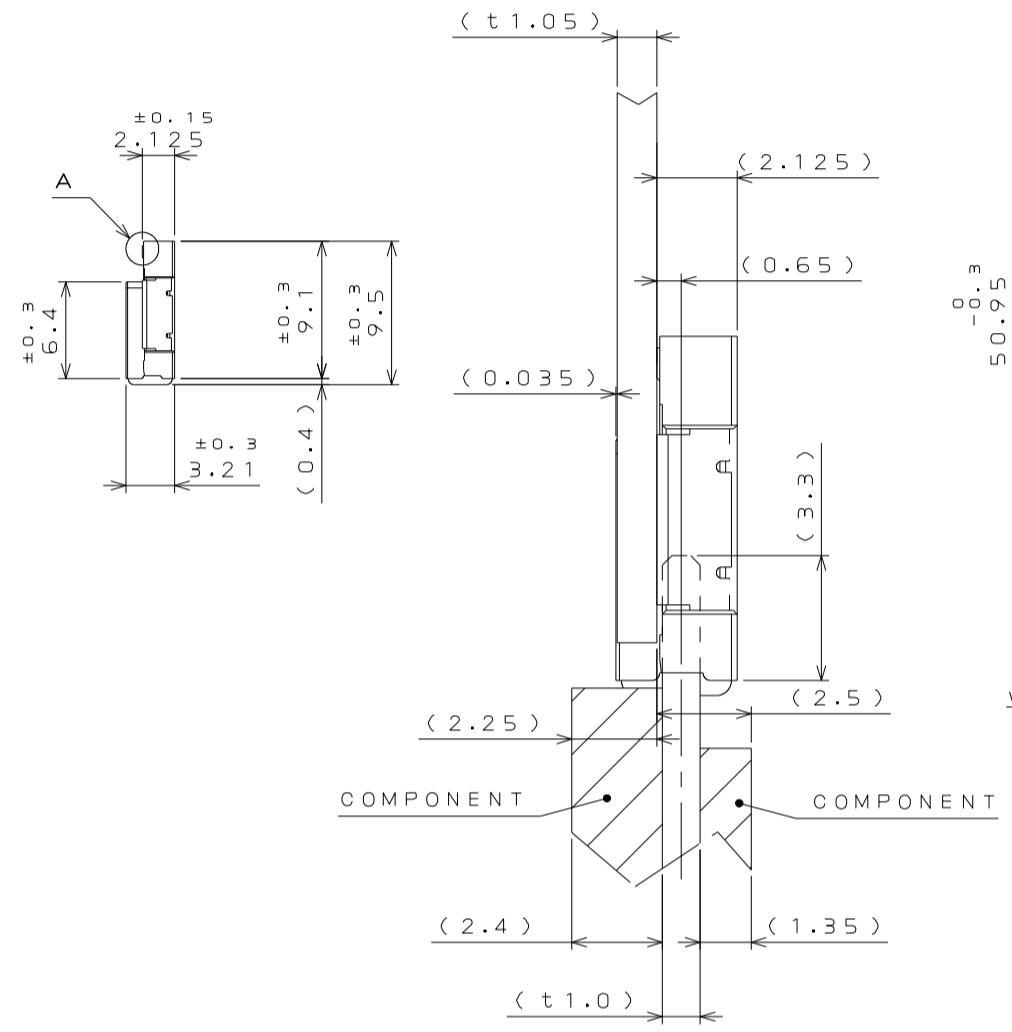


NOTE 1. PRODUCTION LOT No. AS INDICATED.
(Ex.) T901
LOT NUMBER OF CURRENT MONTH
MONTH (1 TO 9 FOR JAN. TO SEPT. RESPECTIVELY,
OCT.:O. NOV.:X. DEC.:Y)
YEAR (LAST DIGIT ONLY)
MANUFACTURE CODE

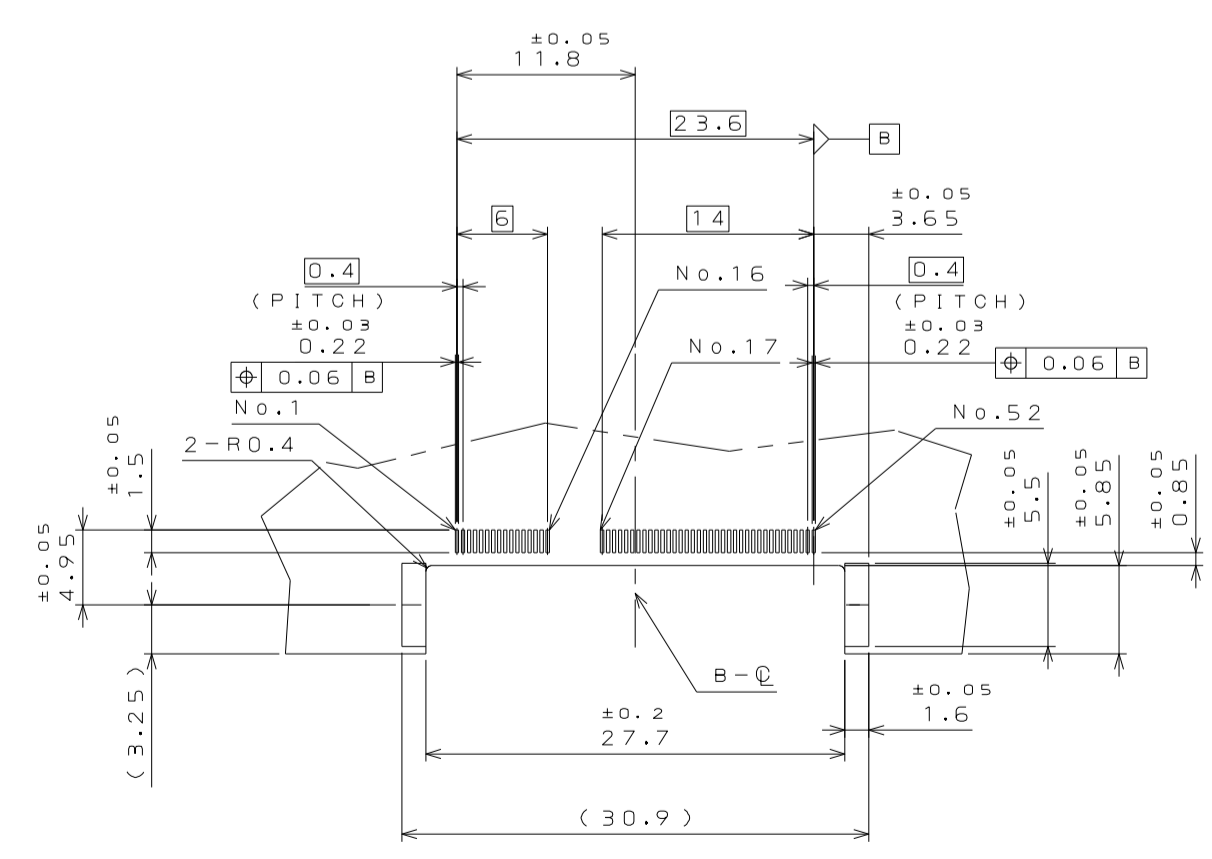
NOTE 2. THE COPLANARITY OF CONTACT AND HOLD-DOWN BE 0.1 MAXIMUM.
NOTE 3. CAV NUMBER AND CORPORATE MARK AS INDICATED.



DETAIL A
(SCALE 10:1)

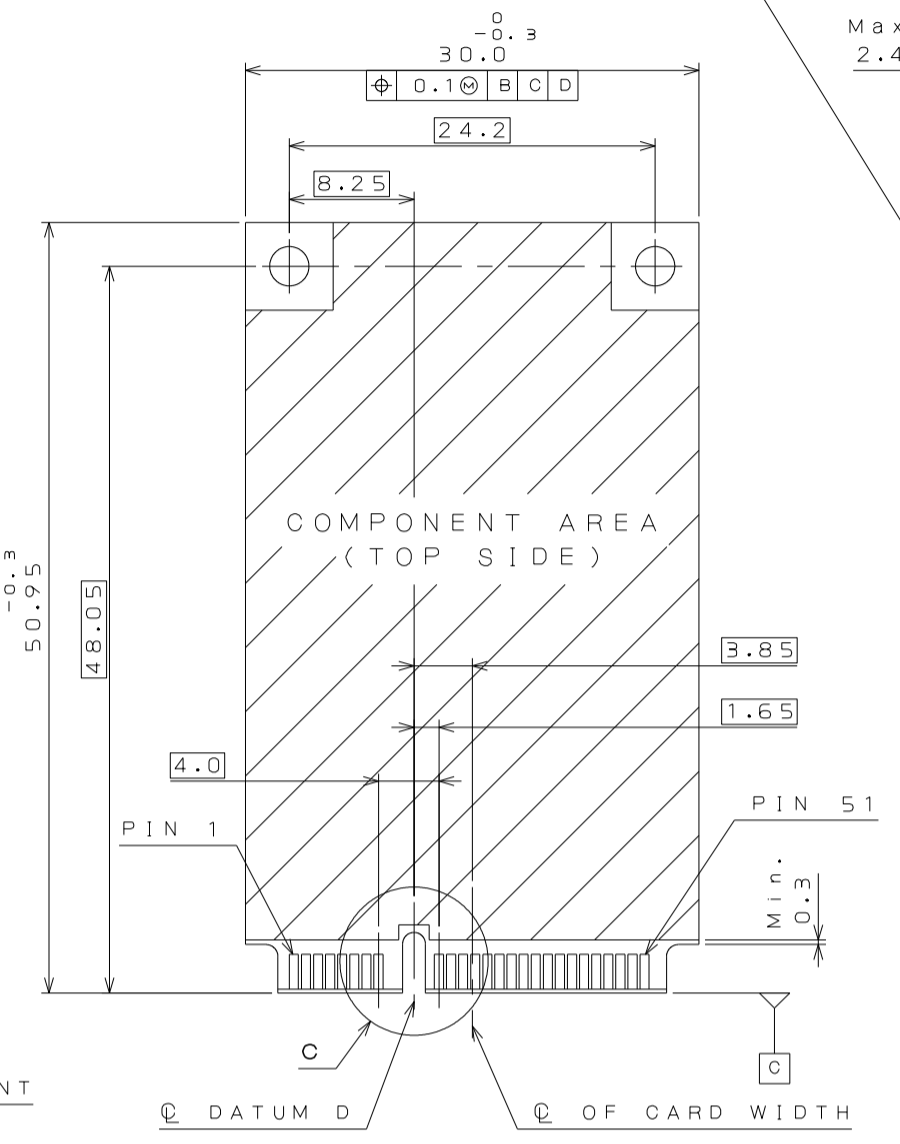


MOUNTING CONDITION (REF.)
実装状態図(参考)



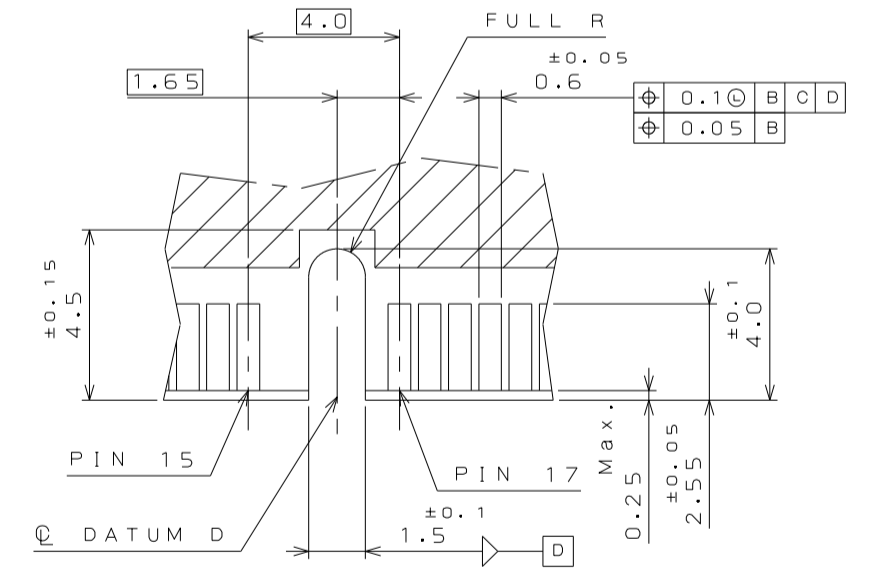
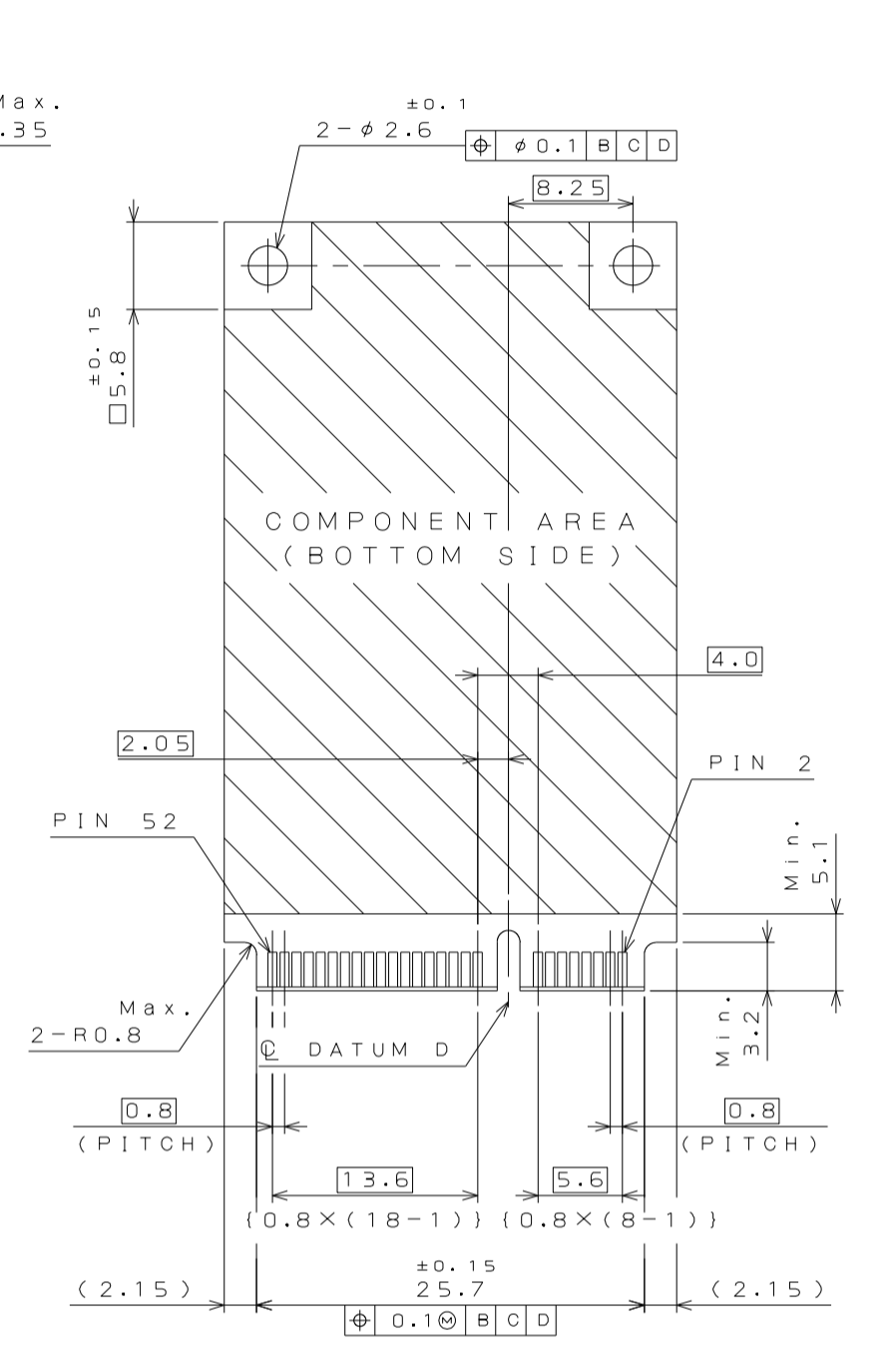
APPLICABLE P.C.B. DIMENSION (REF.)
適合基板寸法(参考)

HATCHED AREAS ILLUSTRATE MAXIMUM AVAILABLE COMPONENT VOLUME.

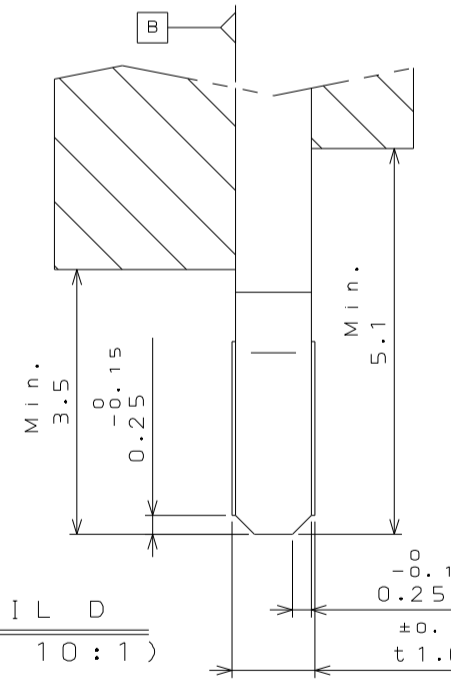


PIN NUMBERING REFERENCE :
ODD PINS - TOP SIDE
EVEN PINS - BOTTOM SIDE

APPLICABLE MINI CARD (REF.)



DETAIL C
(SCALE 5:1)



DETAIL D
(SCALE 10:1)

4	HOLD DOWN	2	COPPER ALLOY	TIN PLATING	
3	INSULATOR	1	THERMOPLASTIC		
2	BOTTOM SIDE CONTACT	26	COPPER ALLOY	CONTACT AREA: Au(0.1μm MIN.) OVER Ni SOLDERING AREA: GOLD FLASH OVER Ni	
1	TOP SIDE CONTACT	26	COPPER ALLOY	CONTACT AREA: Au(0.1μm MIN.) OVER Ni SOLDERING AREA: GOLD FLASH OVER Ni	
符号 NO.	名称 DESCRIPTION	個数 QTY.	材料 MATERIAL	仕上 FINISH	備考 REMARKS
	仕様書(SPECIFICATION)	第1版(ORIGINAL DATE)	16.Feb.2011	スケール(SCALE) 5:1	シリーズ(SERIES) MM60
	製図 DR.			名称(TITLE)	日本航空電子工業株式会社
	公差(GENERAL TOLERANCE)				JAPAN AVIATION ELECTRONICS INDUSTRY, LTD.
	寸法(DIMENSION)	角度(ANGLES)			図面番号(DRAWING NO.) SJ111356
	. ±0.8	° ±			版数 (REV.) 3
	.X ±0.4	X° ±			
	.XX ±0.1				
	.XXX ±				
	製造 DR.				
	担当 CHK.		T.TSUJI		
	査閲 APPD.				
	承認 APPD.		K.IBARAKI		
	質量(MASS)				